

Claims:-

1. A process of manufacturing a cover for an electronic device, the process comprising forming the cover member for the device, incorporating electrical circuitry into the cover during the formation, and providing on the cover an integral connector structure for connecting the electrical circuitry to an electronic component.
2. A process according to claim 1, wherein the step of incorporating the electrical circuitry into the cover comprises forming an electrical circuitry element, arranging the electrical circuitry element in a mould and moulding the cover onto the electrical circuitry element.
3. A process according to claim 2, wherein the moulding of the cover comprises introducing a plastics material into the mould after the electrical circuitry element is arranged in the mould, and forming the connector structure with the cover in the mould.
4. A process according to claim 3, wherein the plastics material is introduced into the mould by injection.
5. A process according to claim 1, wherein the step of incorporating the electrical circuitry into the cover comprises forming a first part of the cover in a first moulding operation, and forming a second part of the cover in a second moulding operation, the second moulding operation comprising forming a precursor for the electrical circuitry, and thereafter applying an electroconductive material to the precursor to form the electrical circuitry.
6. A process according to claim 5, wherein the integral connector structure is formed on the second part during the second moulding operation.
7. A process according to claim 5, wherein the first moulding operation comprises introducing a first plastics material into the first part of the mould.

8. A process according to claim 5, wherein electroconductive material is a metallic material.

9. A process according to claim 5, wherein a step of applying the electroconductive material comprises plating the electroconductive material onto the precursor.

10. A process according to claim 9, wherein the step of plating the electroconductive material consists of one or both selected from electroplating and electroless plating.

11. A process according to claim 9, wherein the second moulding operation comprises introducing a second plastics material into the mould, the second plastics material carrying a seeding substance to seed the plating of the electroconductive material onto the precursor, the seeding substance comprising metallic particles.

12. A process according to claim 1, wherein the step of incorporating the electrical circuitry into the cover comprises providing a substrate, forming a precursor for the electrical circuitry on the substrate, moulding the substrate to form the cover and then applying an electroconductive material to the precursor to form the electrical circuitry.

13. A process according to claim 12, wherein the step of applying the electroconductive material comprises plating the electroconductive material onto the precursor.

14. A process according to claim 13, wherein the step of plating the electroconductive material consists of one or both selected from electroplating and electroless plating.

15. A process according to claim 13, wherein the step of forming the precursor comprises applying a carrier material to the substrate, the carrier material carrying a seeding substance to seed the plating of the electroconductive

material onto the precursor, the secondary substance comprising metallic particles.

16. A process according to claim 15, wherein the carrier material comprises an ink and the step of applying the carrier material to the substrate comprises printing the carrier material on the substrate.

17. A process according to claim 12, wherein the substrate comprises a plastics material and the step of moulding the substrate to form the cover comprises vacuum or press moulding the substrate.

18. A process according to claim 12, wherein the step of providing the connector structure on the cover comprises moulding the connector onto the cover after the substrate has been moulded to form the cover.

19. A process according to claim 1 comprising providing a flexible holding member in the connector structure to hold the electronic component in electrical communication with the electrical circuitry.

20. A process according to claim 19, wherein the flexible holding member comprises a resilient member.

21. A cover for an electronic device, the cover comprising an integral electrical circuitry, and an integral connector structure on the cover for connecting the electrical circuitry to an electronic component.

22. A cover according to claim 21, wherein the electrical circuitry is moulded on the cover.

23. A cover according to claim 22, formed of first and second integrally moulded parts, wherein the second moulded part comprises a precursor for the electrical circuitry.

24. A cover according to claim 23, wherein the second part comprises a precursor for the electrical circuitry, and a layer of an electrically conductive material providing said electrical circuitry.
25. A cover according to claim 25, wherein the electroconductive material comprises a plated metallic material.
26. A cover according to claim 21, wherein the cover is provided with a precursor for the electrical circuitry applied thereto, and an electroconductive material on the precursor.
27. A cover according to claim 27, wherein the precursor is printed onto the cover and comprises a carrier material carrying a sealing substance.
28. A cover arrangement according to claim 28, wherein the electroconductive material is plated onto the carrier material.
29. A cover according to claim 29, wherein the electroconductive material is a metallic material.
30. A cover according to claim 21, wherein the connection structure includes a holding member to hold the electronic component in electrical communication with the electrical circuitry.
31. A cover arrangement according to claim 31, wherein the flexible holding member comprises a resilient spring.
32. A cover arrangement according to claim 21, wherein the connector structure is formed on the cover by being moulded with the cover.